Product Change Notification: MFOL-14JQZE577

Date:

22-Apr-2026

Product Category:

32-Bit Microcontrollers

Notification Subject:

CCB 8226 Final Notice: Qualification of MMT as an additional assembly site for selected PIC32MM0064GPM028, PIC32MM0256GPM028, PIC32MM0128GPM028, PIC32MM0016GPL028, PIC32MM0064PGL028, PIC32MM0032GPL028, and PIC32MM0064GPL028 device families available in 28L UQFN (4x4x0.6mm) package.

Affected CPNs:

MFOL-14JQZE577_Affected_CPN_04222026.pdf
MFOL-14JQZE577_Affected_CPN_04222026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for selected PIC32MM0064GPM028, PIC32MM0256GPM028, PIC32MM0128GPM028, PIC32MM0016GPL028, PIC32MM0064PGL028, PIC32MM0032GPL028, and PIC32MM0064GPL028 device families available in 28L UQFN (4x4x0.6mm) package.

Pre and Post Summary Changes:

110x110 mils

	Pre Change	Post Change	Change (Yes/No)

<table>
<tr><td>Assembly Site</td><td colspan="2">ASE Inc.(ASE)</td><td colspan="2">ASE Inc.(ASE)</td><td>Microchip Technology Thailand (Branch)
(MMT)</td><td>Yes</td></tr>
<tr><td>Wire Material</td><td colspan="2">CuPdAu</td><td colspan="2">CuPdAu</td><td>CuPdAu</td><td>No</td></tr>
<tr><td>Die Attach Material</td><td colspan="2">FH-900 (PFAS Free)</td><td colspan="2">FH-900 (PFAS Free)</td><td>HR-5104T-25 (PFAS Free)</td><td>Yes</td></tr>
<tr><td>Molding Compound Material</td><td>G700LA</td><td>G631H</td><td>G700LA</td><td>G631H</td><td>G700Y</td><td>Yes</td></tr>
<tr><td>Lead-Frame Material</td><td colspan="2">C7025</td><td colspan="2">C7025</td><td>EFTEC64T</td><td>Yes</td></tr>
<tr><td>Lead-Frame Paddle Size</td><td colspan="2">83x83 mils</td><td colspan="2">83x83 mils</td><td>110x110 mils</td><td>Yes</td></tr>
<tr><td>Lead-Frame Lead Lock</td><td colspan="2">No</td><td colspan="2">No</td><td>Yes</td><td>Yes</td></tr>
<tr><td>Lead-Frame Design</td><td colspan="5">See Pre and Post Change Summary attachment for comparison.</td><td>Yes</td></tr>
</table>

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 09 July 2026 (date code: 2628)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	April 2026	>	**July 2026**

Work Week	14	15	16	17	18		27	28	29	30	31
Qual Report Availability				X							
Final PCN Issue Date				X							
Estimated Implementation Date								X			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: April 22, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-14JQZE577_Pre and Post Change Summary.pdf
PCN_MFOL-14JQZE577_Qual_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

PIC32MM0256GPM028T-I/M6

PIC32MM0256GPM028-E/M6

PIC32MM0064GPM028-E/M6

PIC32MM0128GPM028-E/M6

PIC32MM0016GPL028-E/M6

PIC32MM0064GPL028-I/M6

PIC32MM0032GPL028-I/M6

PIC32MM0016GPL028-I/M6

PIC32MM0016GPL028T-I/M6

PIC32MM0064GPL028T-I/M6

PIC32MM0032GPL028T-I/M6

PIC32MM0032GPL028-E/M6

PIC32MM0064GPL028-E/M6

PIC32MM0064GPM028T-I/M6044

PIC32MM0256GPM028T-I/M6043

PIC32MM0256GPM028-I/M6

PIC32MM0128GPM028-I/M6

PIC32MM0064GPM028-I/M6

PIC32MM0128GPM028T-I/M6

PIC32MM0064GPM028T-I/M6

CCB 8226
Pre and Post Change Summary
PCN #: MFOL-14JQZE577

A Leading Provider of Smart, Connected and Secure Embedded Control Solutions

Pre and Post Change – Lead Frame Design

ASE	MMT

ASE

Note: *Not To Scale

Lead-Frame Material	C7025
Lead-Frame Lead lock	No

MMT

Lead-Lock

Note: *Not To Scale

Lead-Frame Material	EFTEC64T
Lead-Frame Lead lock	Yes

*Note: Mold compound materials fills the leadlock hole, which provides improved protection against moisture penetration along the edge of the leads (pins) of the package.

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QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: MFOL-14JQZE577

Date:
March 24, 2026

Qualification of MMT as an additional assembly site for selected SST26WF016B, SST26WF016BA, SST26WF080B, SST26WF080BA, SST26WF040B, SST26WF040BA, SST26VF032B, SST26VF032BA, SST26WF064C, SST26VF064BEUI, SST26VF016B, SST26VF080A, SST26VF040A, SST26VF020A, SST25VF080B, SST25VF020B, SST25VF040B, SST26VF064B, SST26VF064BA and SST25PF020B device families available in 8L WSON (6x5x0.8mm) package.
The PIC32MM0064GPM028, PIC32MM0256GPM028, PIC32MM0128GPM028, PIC32MM0016GPL028, PIC32MM0064PGL028, PIC32MM0032GPL028, and PIC32MM0064GPL028 device families available in 28L UQFN (4x4x0.6mm) package. This is Q006 Grade 1 Qualification and will qualify by similarity (QBS).

Package Qualification Report

Purpose: Qualification of MMT as an additional assembly site for selected SST26WF016B, SST26WF016BA, SST26WF080B, SST26WF080BA, SST26WF040B, SST26WF040BA, SST26VF032B, SST26VF032BA, SST26WF064C, SST26VF064BEUI, SST26VF016B, SST26VF080A, SST26VF040A, SST26VF020A, SST25VF080B, SST25VF020B, SST25VF040B, SST26VF064B, SST26VF064BA and SST25PF020B device families available in 8L WSON (6x5x0.8mm) package. The PIC32MM0064GPM028, PIC32MM0256GPM028, PIC32MM0128GPM028, PIC32MM0016GPL028, PIC32MM0064PGL028, PIC32MM0032GPL028, and PIC32MM0064GPL028 device families available in 28L UQFN (4x4x0.6mm) package. This is Q006 Grade 1 Qualification and will qualify by similarity (QBS).

CCB No. 7830 and 8226

Misc.	**Assembly site**	MMT
	BD Number	BD-003648-01
	MP Code (MPC)	S01029U3XV01
	Part Number (CPN)	SST26VF064B-104V/MF70SV01
	Assembly Shipping Media (T/R, Tube/Tray)	Tube
	Base Quantity Multiple (BQM)	98
Lead-Frame	**Paddle size**	150x173
	Material	A194
	DAP Surface Prep	Bare Cu
	Treatment	Roughening LF
	Process	Etched LF
	Lead-lock	Dimple
	Part Number	10100878
	Lead Plating	Matte Tin
Bond Wire	**Material**	CuPdAu
Die Attach	**Part Number**	QMI519 (PFAS Free)
	Conductive	Yes
MC	**Part Number**	G700LTD
PKG	**PKG Type**	WSON
	Pin/Ball Count	8
	PKG width/size	6x5x0.8mm

Package Qualification Report

Manufacturing Information:

Assembly Lot ID
MMT-263800307.000
MMT-263801083.000
MMT-263801089.000

Conclusion:

Qualification of S0102 mask / SST26VF064B-104V/MF70SV01 product / 0.8 mil CuPdAu wire in 8L WSON 6x5x0.8mm (U3X) package at MMT site is qualified for MSL1 at 260ºC as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards

Package Qualification Report

Moisture Soak Precondition Prior to Stresses

Test Method	JESD22-A113, JEDEC J-STD-020		
Test Condition	**MSL1**: 150ºC 24 hours Bake, 168 hours Moisture Soak at 85ºC/85%RH, 3x Reflow at 260ºC		
Required Sample Size	231 units each lot / 3 lots; refer to FRM-39000		
Lot ID	**R2600052-1 MMT-263800307.000**	**R2600052-2 MMT-263801083.000**	**R2600052-3 MMT-263801089.000**
Electrical Results (Fail / Pass)	0/231	0/231	0/231
Electrical Test Tester: NEXTEST_GV2X	25°C, 105°C, and 125°C		
Result:	Passed		

High Temp Storage

Test Method	JESD22-A103		
Test Condition	175°C / 500 hours		
Required Sample Size	45 units each lot / 3 lots; refer to FRM-39000		
Lot ID	**R2600052-1 MMT-263800307.000**	**R2600052-2 MMT-263801083.000**	**R2600052-3 MMT-263801089.000**
Electrical Results (Fail / Pass)	0/45	0/45	0/45
Electrical Test Tester: NEXTEST_GV2X	25°C		
Result:	Passed		

Package Qualification Report

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-55ºC / +150ºC Air to Air / 1000 Cycles		
Required Sample Size	77 units each lot / 3 lots; WBP/WBS & IPA, refer to FRM-39000		
Lot ID	**R2600052-1 MMT-263800307.000**	**R2600052-2 MMT-263801083.000**	**R2600052-3 MMT-263801089.000**
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: NEXTEST_GV2X	25°C, 105°C, and 125°C		
Result:	Passed		

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130ºC / 85%RH / 96 hours / Bias Voltage: 3.6V		
Required Sample Size	77 units each lot / 3 lots; WBP/WBS & IPA, refer to FRM-39000		
Lot ID	**R2600052-1 MMT-263800307.000**	**R2600052-2 MMT-263801083.000**	**R2600052-3 MMT-263801089.000**
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: NEXTEST_GV2X	25°C, 105°C, and 125°C		
Result:	Passed		

Package Qualification Report

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130ºC / 85%RH / 192 hours / Bias Voltage: 3.6V		
Required Sample Size	77 units each lot / 3 lots; WBP/WBS & IPA, refer to FRM-39000		
Lot ID	**R2600052-1 MMT-263800307.000**	**R2600052-2 MMT-263801083.000**	**R2600052-3 MMT-263801089.000**
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: NEXTEST_GV2X	25°C, 105°C, and 125°C		
Result:	Passed		

Unbiased HAST

Test Method	JESD22-A118		
Test Condition	+130ºC / 85%RH / 96 hours		
Required Sample Size	77 units each lot / 3 lots; IPA, refer to FRM-39000		
Lot ID	**R2600052-1 MMT-263800307.000**	**R2600052-2 MMT-263801083.000**	**R2600052-3 MMT-263801089.000**
Electrical Results (Fail / Pass)	0/77	0/77	0/77
IPA Decapsulation	0/5	0/5	0/5
Electrical Test Tester: NEXTEST_GV2X	25°C		
Result:	Passed		

Package Qualification Report

Solderability (0 Hr) Method 1: Dip and Look

Test Method	J-STD-002 / JESD22B-102
Test Condition / Criteria	Pb-free 8 hours Steam age. Dip at 245ºC, 100% leads >95% lead coverage
Required Sample Size	22 units / 1 lot
Visual Result (Fail / Pass)	0/22
Result:	Passed

Physical Dimension (0Hr)

Test Method	JESD22 B100 and B108
Test Criteria	Within package diagram dimension
Required Sample Size	10 units each lot / 3 lots
Result (Fail / Pass)	0/30 - **Passed**

Wire Pull

Test Method	Mil. Std. 883-2011
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5 - **Passed**

Bond Shear

Test Method	CDF-AEC-Q100-001
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5 - **Passed**

QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: MFOL-14JQZE577

Date:
March 8, 2024

Qualification of MMT as an additional assembly site for selected PIC32MM0064GPM028, PIC32MM0256GPM028, PIC32MM0128GPM028, PIC32MM0016GPL028, PIC32MM0064PGL028, PIC32MM0032GPL028, and PIC32MM0064GPL028 device families available in 28L UQFN (4x4x0.6mm) package will qualify by similarity (QBS).

PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MMT as an additional assembly site for selected PIC32MM0064GPM028, PIC32MM0256GPM028, PIC32MM0128GPM028, PIC32MM0016GPL028, PIC32MM0064PGL028, PIC32MM0032GPL028, and PIC32MM0064GPL028 device families available in 28L UQFN (4x4x0.6mm) package will qualify by similarity (QBS).
CN	E000186953
QUAL ID	R2301692 Rev. A
MP CODE	WACU1MPWXAXF
Part No.	DSPIC33CK64MP102-H/M6
Bonding No.	BD-001593 Rev. 01
CCB No.	6430 and 8226
<u>Package</u>	
Type	28L UQFN
Package size	4 x 4 x 0.6 mm
<u>Lead Frame</u>	
Paddle size	110 x 110 mils
Material	EFTEC64T
Surface	Bare Cu
Treatment	Roughened
Process	Etched
Lead Lock	Yes
Part Number	10102846
<u>Material</u>	
Epoxy	HR-5104T-25
Wire	CuPdAu wire
Mold Compound	G700LTD
Plating Composition	Matte Sn

PACKAGE QUALIFICATION REPORT

Manufacturing Information:

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-243000971.000	TC14923444394.200	2343RYG
MMT-243001383.000	TC14923444394.200	2343UHK
MMT-243001384.000	TC14923444394.200	2343UHP

Result [X] Pass [ ] Fail [ ] ____________________

28L UQFN (4x4x0.6 mm) assembled by MMT pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	**Electrical Test:** +25°C, 85°C, 125°C and 150°C System: J750	JESD22-A113	693(0)	0/693		Good Devices
	Bake 150°C, 24 hrs. System: CHINEE	JIP/ IPC/JEDEC J-STD-020E		693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test: +25°C, 85°C, 125°C and 150°C System: J750		693(0)	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	**Stress Condition:** -65°C to +150°C, 500 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104		0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +85°C, 125°C and 150°C System: J750		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>2.50 grams)		15(0)	0/15	Pass	
UNBIASED-HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: J750		231(0)	0/231	Pass	77 units / lot
HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. **Bias Volt:** 3.6 Volts System: HAST 6000X	JESD22-A110		0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C, 85°C, 125°C and 150°C System: J750		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 504 hrs. System: CHINEE	JESD22-A103		0/135		45 units / lot
	Electrical Test: +25°C, 85°C, 125°C and 150°C System: J750		135(0)	0/135	Pass	
Bond Strength Data Assembly	Wire Pull (>2.50 grams)	Mil. Std. 883-2011	30(0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	CDF-AEC-Q100-001	30(0) bonds	0/30	Pass	